

# END-OF-LIFE PREDICTION FOR SOLDER JOINTS IN ELECTRONIC SYSTEMS EXPERIENCING LOW-CYCLE FATIGUE UNDER IMPACT LOADING

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# OUTLINE

- Background and Introduction
- Methodology
- Experimental approach
- Results
- Conclusions and future work



# HIGH-RATE MECHANICAL SHOCK

- Mechanical Shock
  - Sudden change in force, position, velocity, or acceleration[1]
  - Induces transient states in the system [1]
  - Can excite system frequencies [1]
  - Can lead to unpredictable responses within the structural integrity of components



Blast against civil structures



Automotive impact and crashes

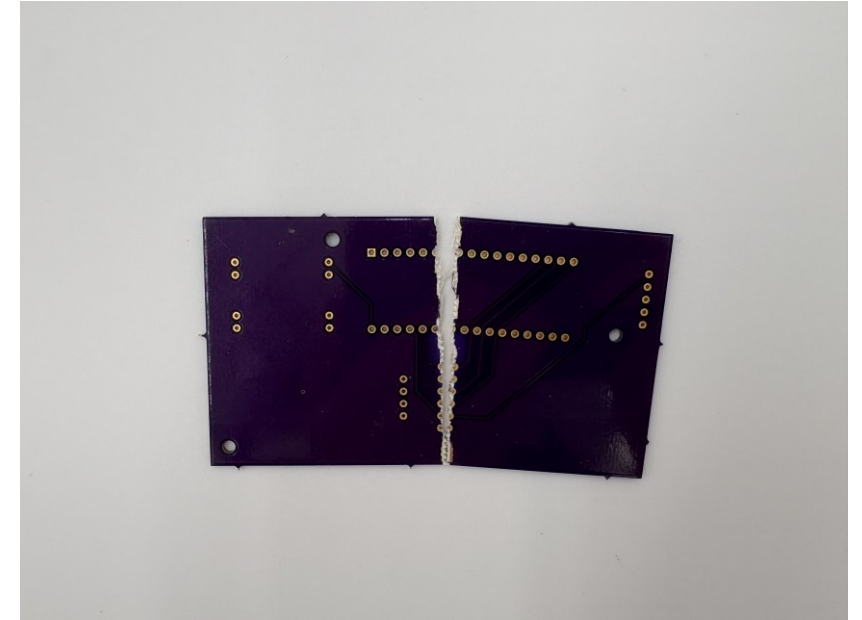


High Speed aircraft and airframes



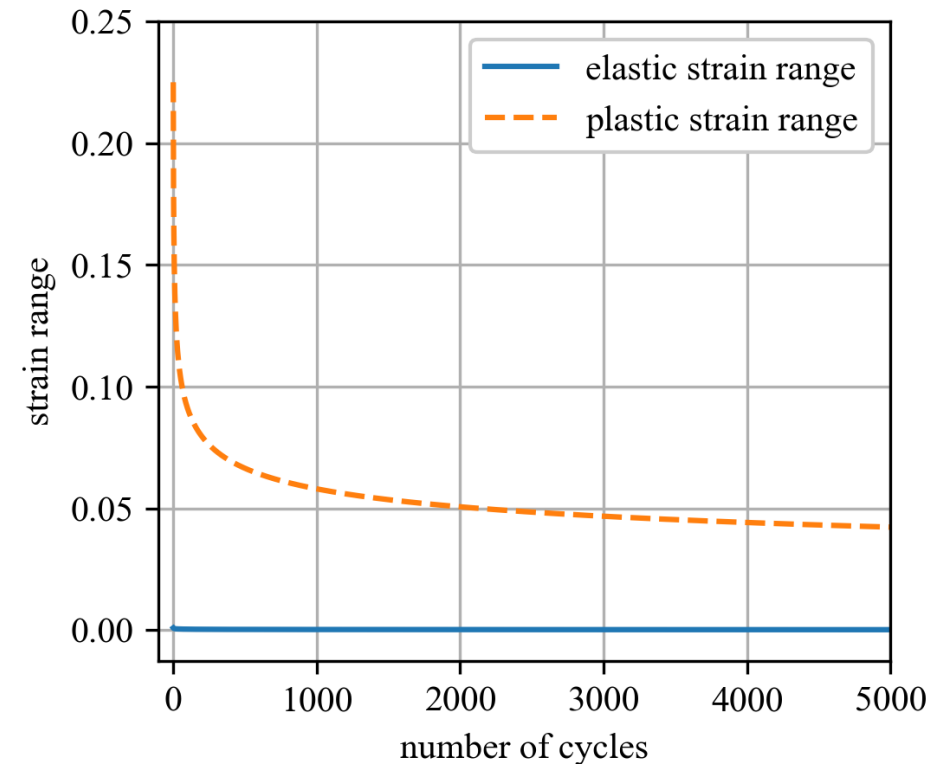
# INTRODUCTION

- Importance:
  - Systems subject to fatigue can experience sudden failure
- Problem:
  - Repeat inspection is not always practical
- Proposal:
  - Construct an algorithm to estimate remaining useful life of system
- Objective:
  - Track remaining useful life of system across intermittent impacts



# BACKGROUND - FATIGUE

- Fatigue
  - Load applied over time
  - Can cause sudden structural failure



Example strain-life curve





# BACKGROUND – MODELING FATIGUE

## Initiation life estimation

- Simulates fatigue damage at points of stress concentration
- Models when a crack occurs
- Modeled through stress-life or strain-life

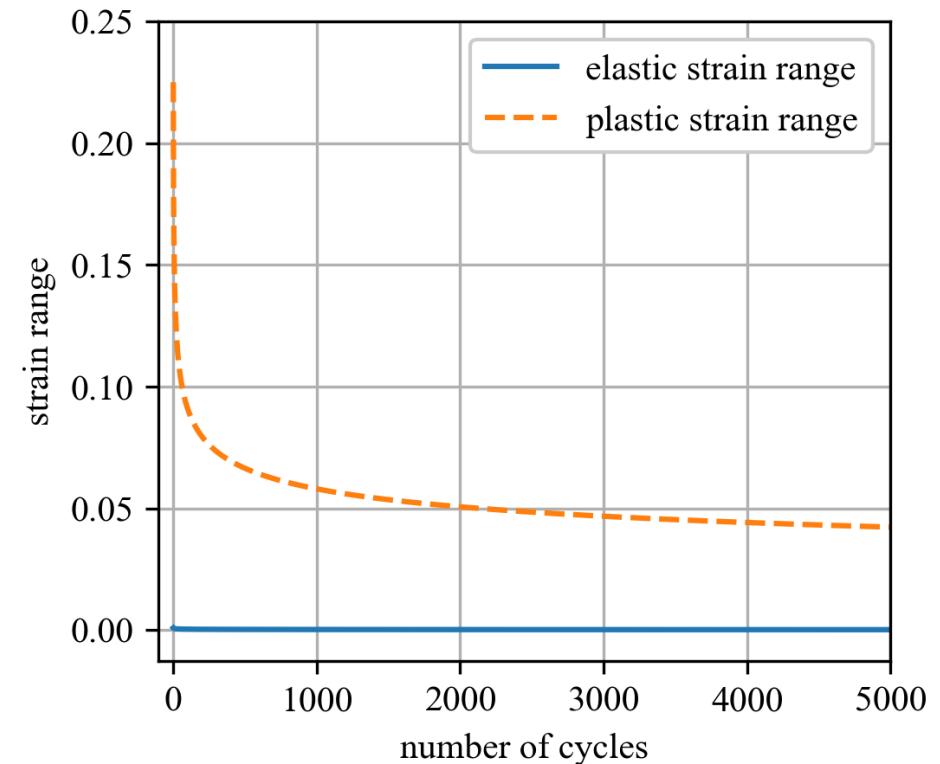
## Propagation life estimation

- Tracks length of crack in material
- Models when crack grows beyond critical length
- Modeled through fracture mechanics



# BACKGROUND – FATIGUE

- Strain-life method
  - Estimates damage from strain amplitude
  - Better for low-cycle fatigue
- Elastic strain
  - $\frac{\Delta \epsilon_e}{2} = \frac{K}{E} \cdot (2N)^{-B_0}$
- Plastic strain
  - $\frac{\Delta \epsilon_p}{2} = \epsilon_f \cdot (2N)^{-\beta_0}$
- Coffin-Manson Relation
  - $\frac{\Delta \epsilon}{2} = \frac{\Delta \epsilon_e}{2} + \frac{\Delta \epsilon_p}{2}$

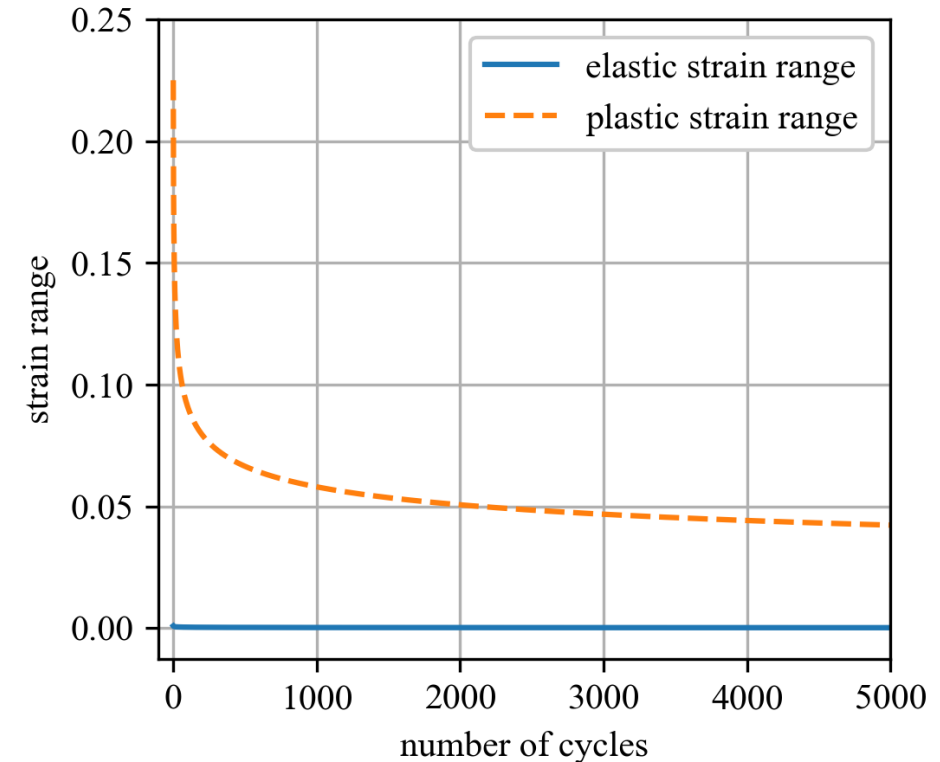


Example strain-life curve



# BACKGROUND – FATIGUE SUMMARY

- Fatigue is damage over time
- Strain splits into plastic and elastic component
- Both represented by exponential decay functions



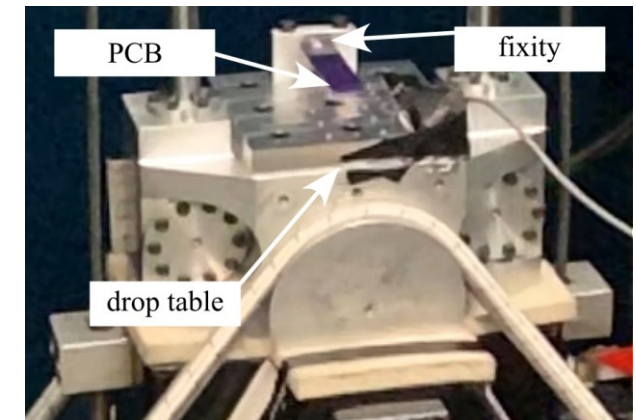
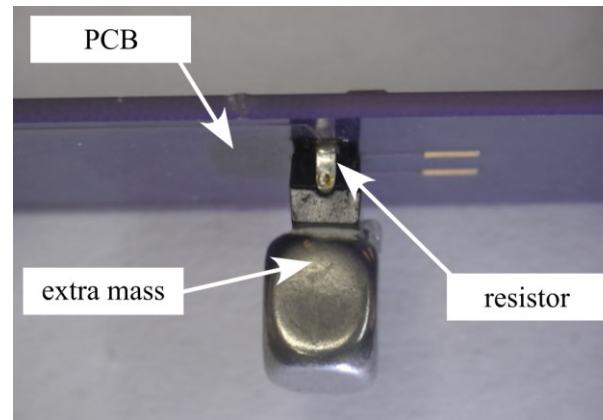
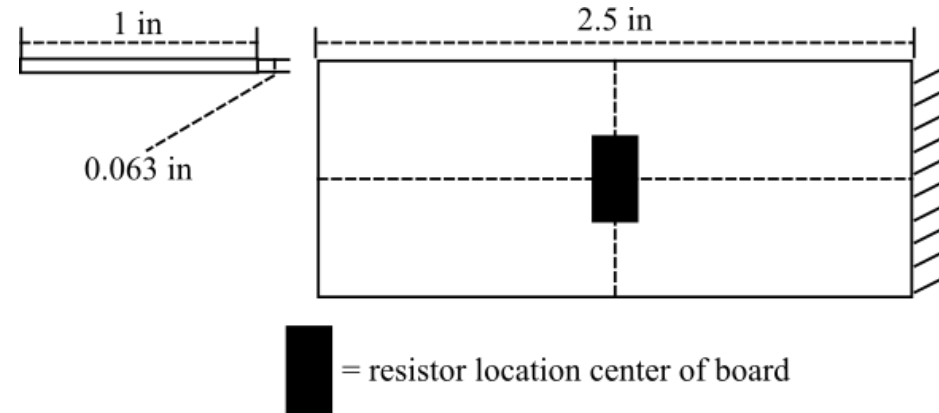
Example strain-life curve





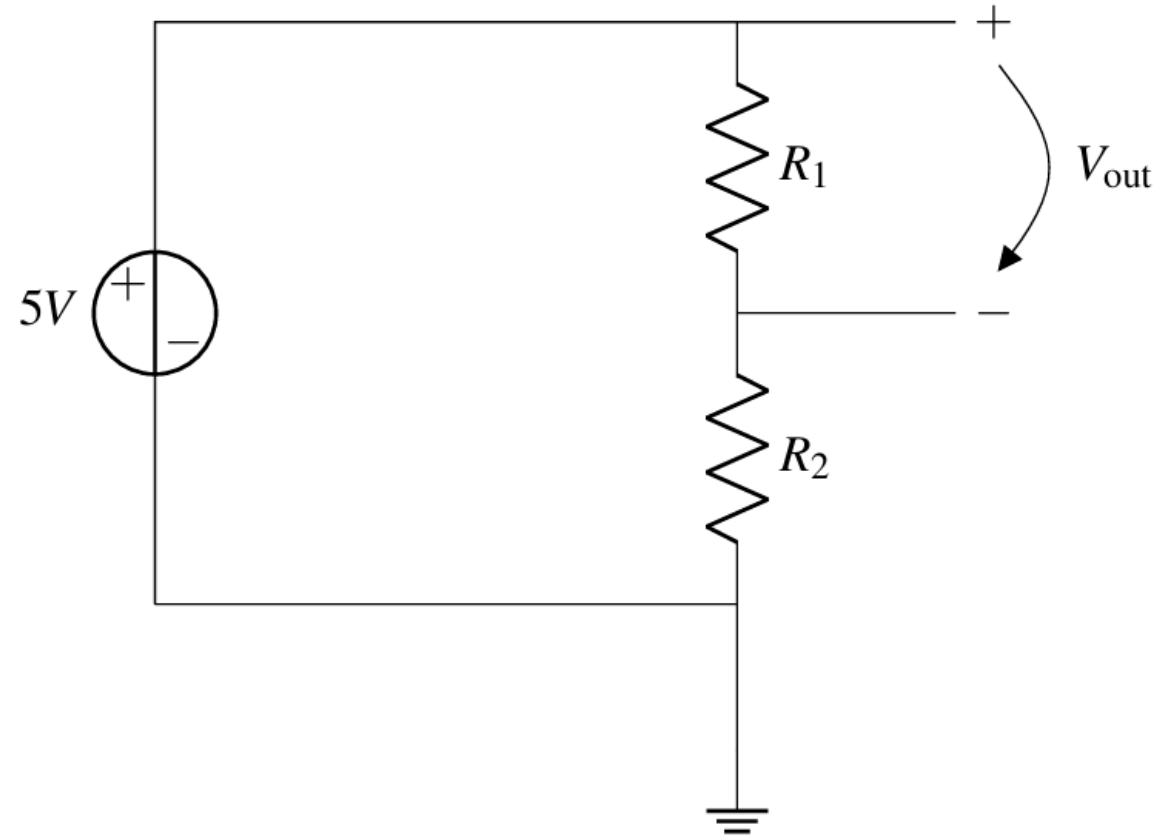
# METHODOLOGY

- Sensor breakdown:
  - Piezoresistive accelerometer
  - 2 strain gauges
  - Resistor/mass
    - Voltage divider circuit
- High-speed camera



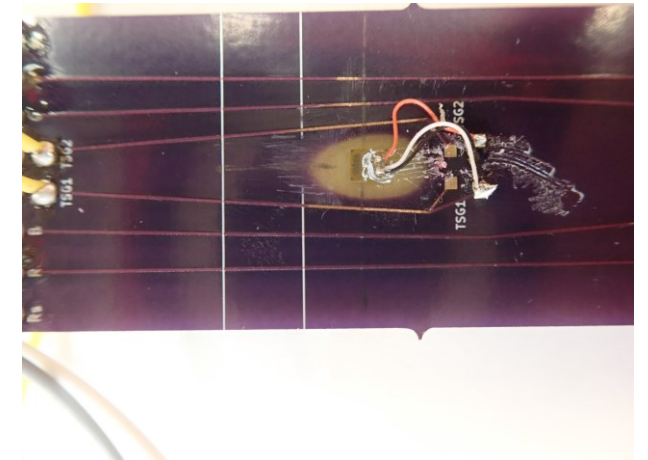
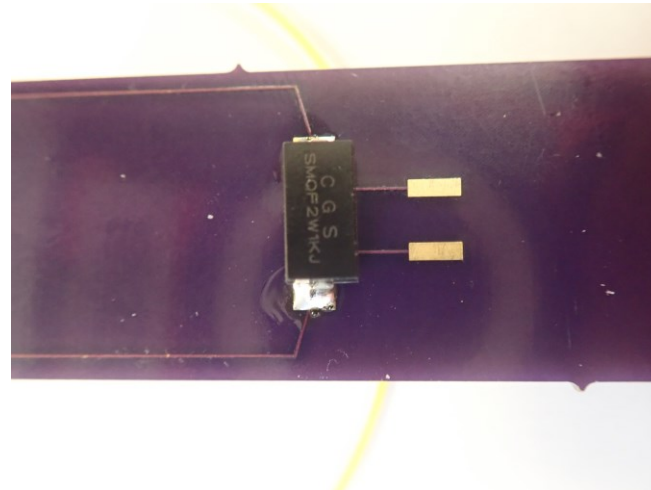
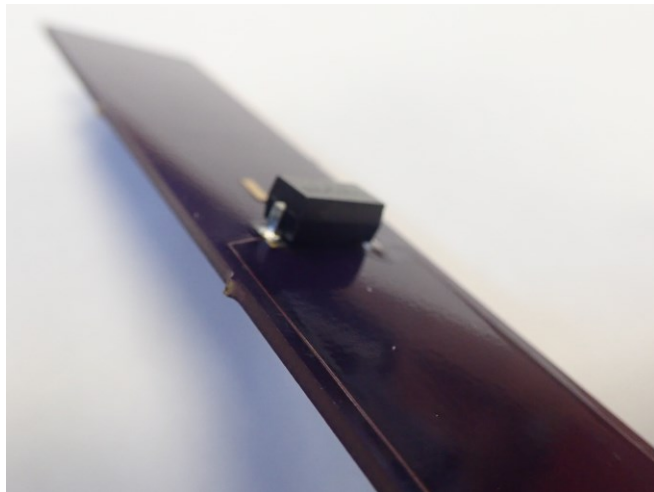
# METHODOLOGY

- Resistor circuit used to get a time reference on the exact moment of failure
  - Voltage divider keeps a 2.5 V signal until failure, which then drops to 0 V



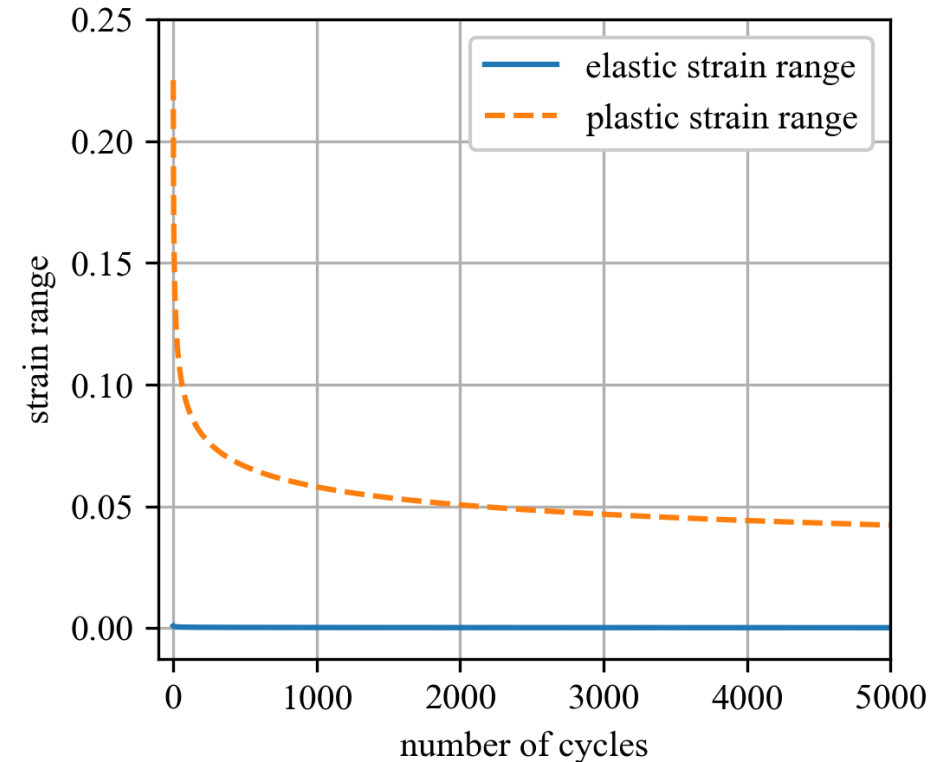
# METHODOLOGY

Material	Density (lb/ft <sup>3</sup> )	Young's Modulus (psi)	Poisson ratio
FR4	118.64	2,697,707	0.2



# METHODOLOGY

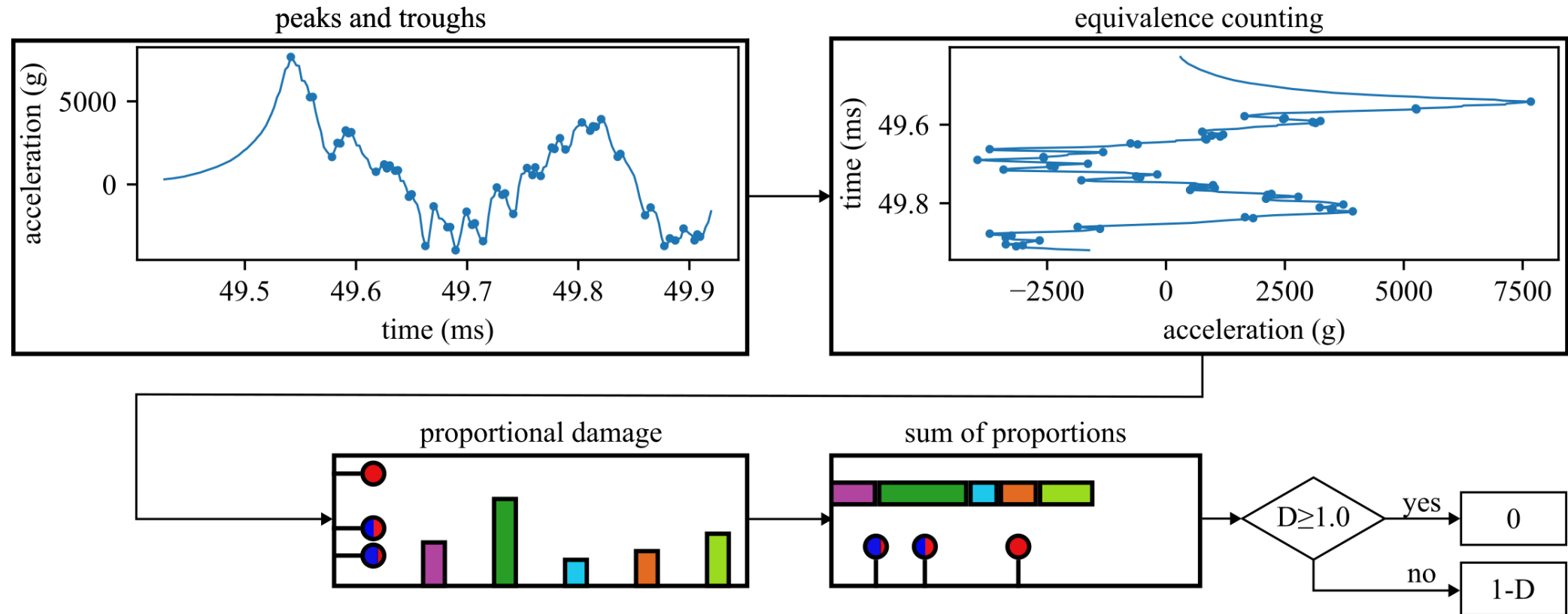
- Assumes constant strain amplitude
- Miner's rule[2]
  - Damage from strain cycles are independent
  - Order of strain cycles does not matter



Example strain-life curve

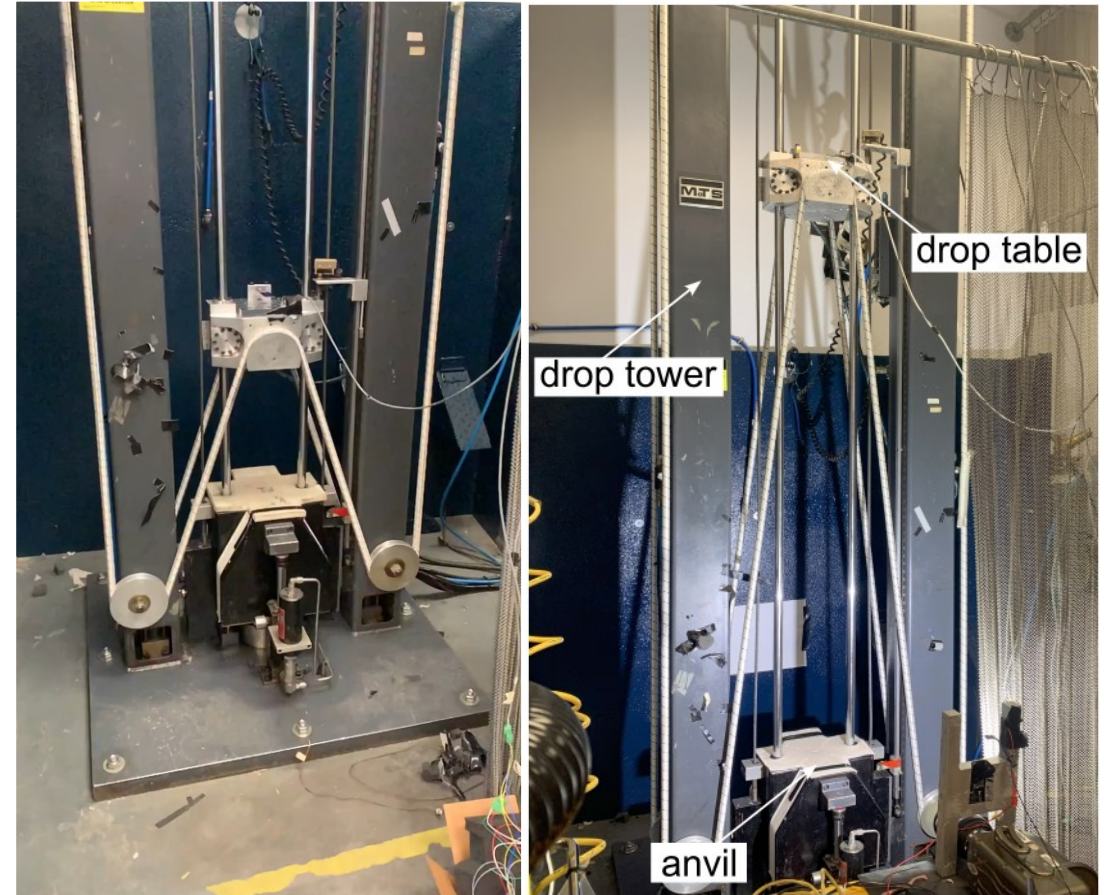


# METHODOLOGY



# EXPERIMENTAL APPROACH

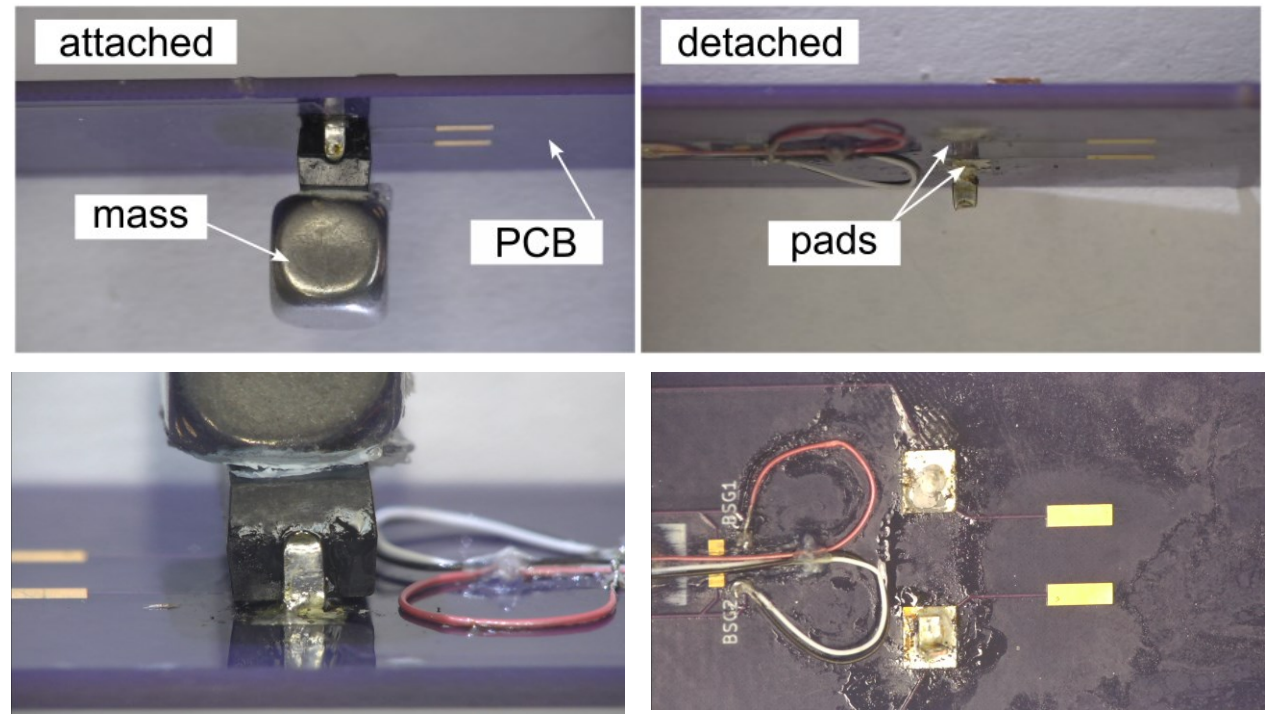
- Drop tower (simulates high-rate impacts)
- Cantilever printed circuit board with sensors
- Resistor/mass component meant to exaggerate the change in dynamics
- Several impacts at varying heights
- Intended to fail the resistor/mass and measure the differences in the response





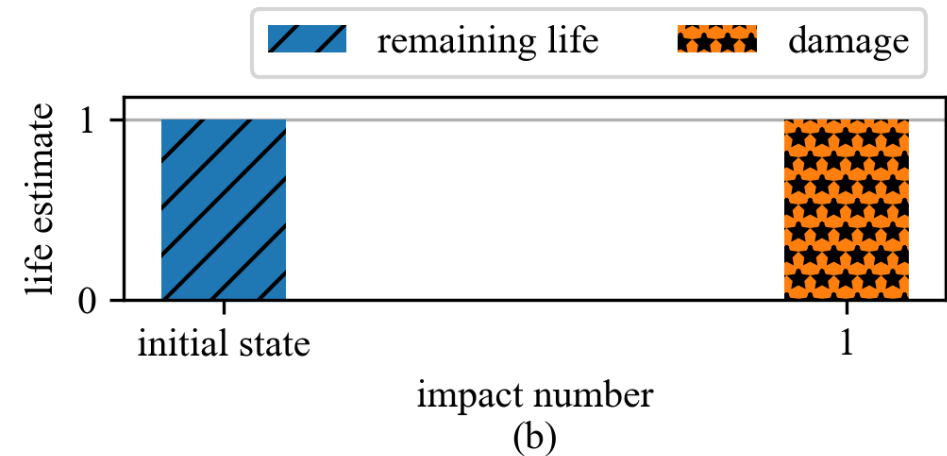
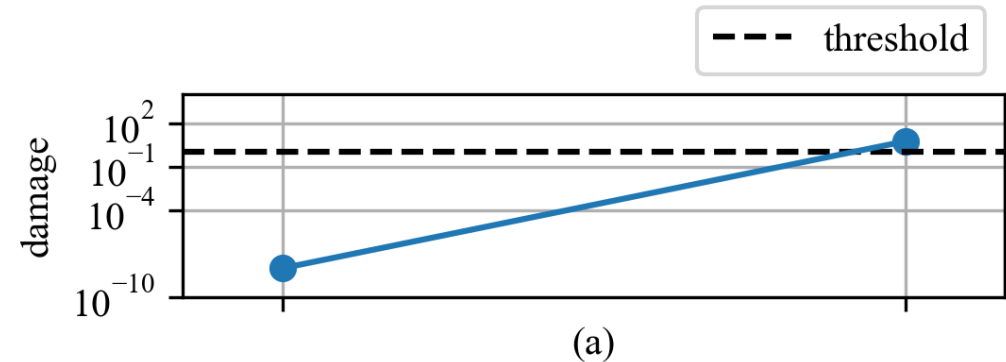
# EXPERIMENTAL APPROACH

- Close-up of PCB and resistor
- Measured resistance for duration of impact
- If resistance was close to 0
  - device failed
  - Replace resistor
- Otherwise
  - Inflict another impact
- Impact set: impacts until device failure



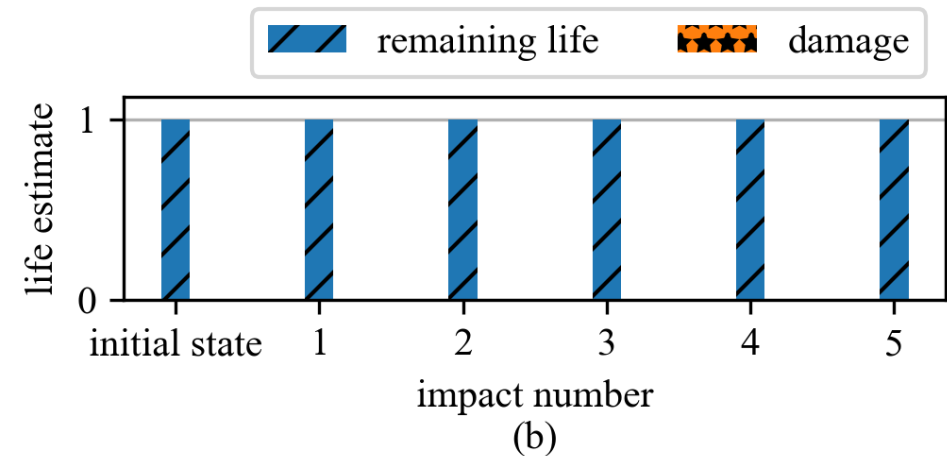
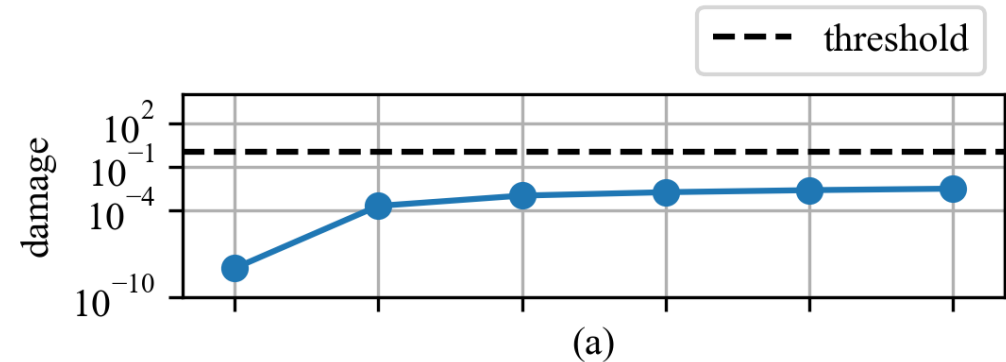
# RESULTS – SET 1

- First impact set
  - Failed after one impact
  - Damage estimate changed 0- >100%



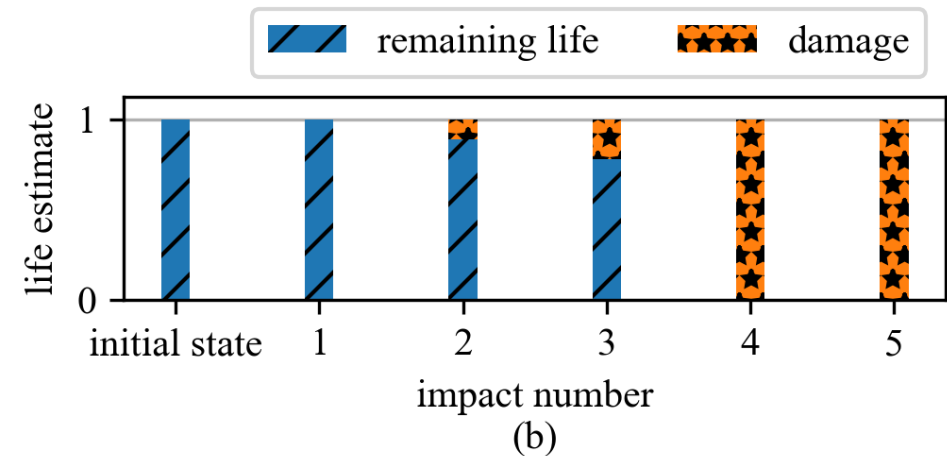
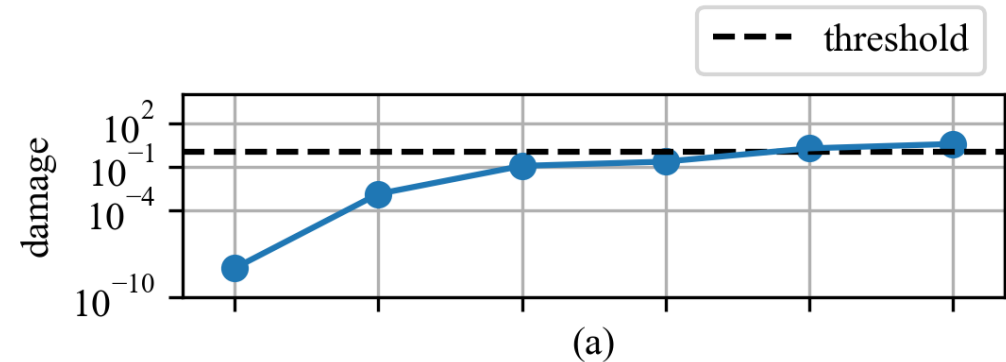
# RESULTS – SET 2

- Second impact set
  - Failed after five impacts
  - Damage estimate remained near 0%
  - Why?
  - Failure occurred at solder-pad interface
  - Our prediction is for solder failure



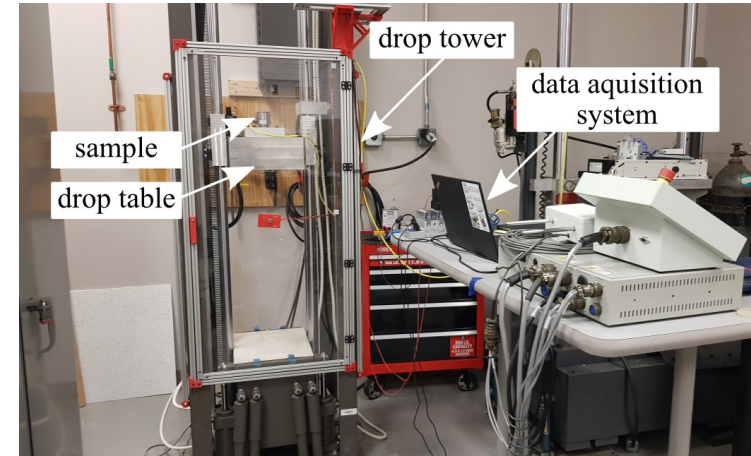
# RESULTS – SET 3

- Third impact set
  - Failed after five impacts
  - Damage estimate changed 0- >100%
  - Survived one more impact than expected



# CONCLUSIONS AND FUTURE WORK

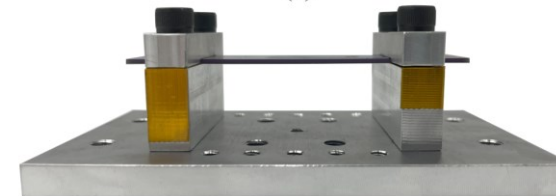
- Algorithm for predicting remaining useful life in solder joints
- Future work
  - Incorporating fatigue from creep[3]
  - Verifying algorithm predictions
  - Generating with varying structural configurations



(a)



(b)



(c)



# ACKNOWLEDGMENT



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# THANKS!

## Open-source Data Set

<https://github.com/High-Rate-SHM-Working-Group/Dataset-9-repeated-impact-testing-of-rectangular-electronic-assembly> [4]



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